

1.5V Drive Pch MOSFET

RZF013P01

●Structure

Silicon P-channel MOSFET

●Features

- 1) Low on-resistance.
- 2) High power package.
- 3) Low voltage drive. (1.5V)

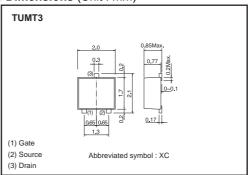
Applications

Switching

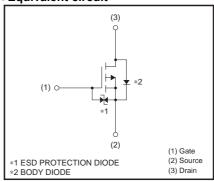
Packaging specifications

	Package	Taping	
Type	Code	TL	
	Basic ordering unit (pieces)	3000	
RZF013P01	0		

●Dimensions (Unit: mm)



●Equivalent circuit



●Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit	
Drain-source voltage		V _{DSS}	-12	V	
Gate-source voltage		V _{GSS}	±10	V	
Drain augrent	Continuous	ΙD	±1.3	A	
Drain current	Pulsed	I _{DP} *1	±5.2	A	
Source current	Continuous	Is *1	-0.6	А	
(Body diode)	Pulsed	I _{SP}	-5.2	А	
Total power dissipation		P _D *2	0.8	W	
Channel temperature		Tch	150	°C	
Range of Storage temperature		Tstg	-55 to +150	°C	

^{*1} Pw≤10µs, Duty cycle≤1%

●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	Rth(ch-a) *	156	°C / W

^{*} When mounted on a ceramic board

^{*2} When mounted on a ceramic board

RZF013P01 Data Sheet

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	Igss	_	-	±10	μΑ	Vgs=±10V, Vps=0V
Drain-source breakdown voltage	V _{(BR) DSS}	-12	-	_	V	I _D = -1mA, V _{GS} =0V
Zero gate voltage drain current	I _{DSS}	_	-	-1	μΑ	V _{DS} = -12V, V _{GS} =0V
Gate threshold voltage	V _{GS (th)}	-0.3	-	-1.0	V	$V_{DS}=-6V$, $I_{D}=-1mA$
Static drain-source on-state resistance		_	190	260	$m\Omega$	I _D = -1.3A, V _G S= -4.5V
	*	_	280	390	$m\Omega$	I _D = -0.6A, V _G S= -2.5V
	R _{DS} (on)	_	400	600	mΩ	I _D = -0.6A, V _G S= -1.8V
		_	530	1060	mΩ	I _D = -0.2A, V _G S= -1.5V
Forward transfer admittance	Y _{fs} *	1.4	-	_	S	V _{DS} = -6V, I _D = -1.3A
Input capacitance	Ciss	-	290	_	pF	Vps= -6V
Output capacitance	Coss	_	28	_	pF	V _{GS} =0V
Reverse transfer capacitance	Crss	_	21	_	pF	f=1MHz
Turn-on delay time	t _{d (on)} *	_	8	_	ns	V _{DD} ≒ −6V
Rise time	tr *	-	10	_	ns	ID= -0.6A
Turn-off delay time	t _{d (off)} *	_	30	_	ns	Vgs= -4.5V RL≒10Ω
Fall time	t _f *	_	9	_	ns	R _G =10Ω
Total gate charge	Qg *	_	2.4	_	nC	V _{DD} ≒-6V R _L ≒4.6Ω
Gate-source charge	Qgs *	_	0.6	_	nC	I _D =-1.3A R _G =10Ω
Gate-drain charge	Q _{gd} *	-	0.4	_	nC	V _{GS} = -4.5V

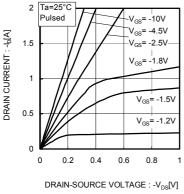
^{*}Pulsed

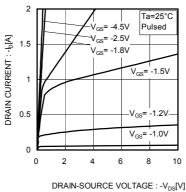
●Body diode characteristics (Source -drain) (Ta=25°C)

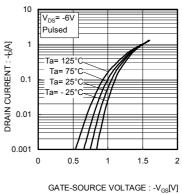
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	Vsp*	_	_	-1.2	V	Is= -1.3A, Vgs=0V

^{*}Pulsed

•Electrical characteristic curves



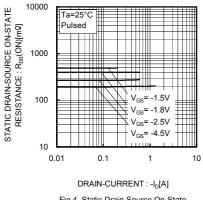




DRAIN-SOURCE VOLTAGE : -V_{DS}[V]
Fig.1 Typical Output Characteristics(I)

Fig.2 Typical Output Characteristics(II)

Fig.3 Typical Transfer Characteristics



STATIC DRAIN-SOURCE ON-STATE

RESISTANCE: 30000

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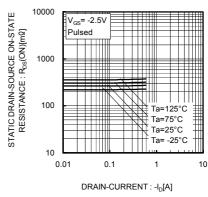
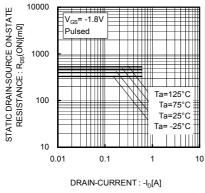
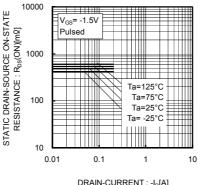


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current(I)

Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(II)

Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(Ⅲ)





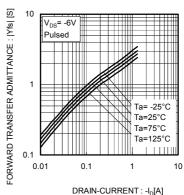
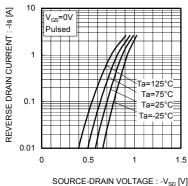
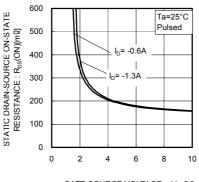


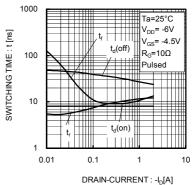
Fig.7 Static Drain-Source On-State
Resistance vs. Drain Current(IV)

DRAIN-CURRENT : -I_D[A]
Fig.8 Static Drain-Source On-State
Resistance vs. Drain Current(V)

Fig.9 Forward Transfer Admittance
vs. Drain Current



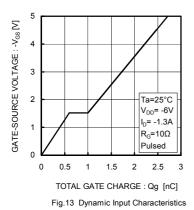




SOURCE-DRAIN VOLTAGE : -V_{SD} [V] Fig.10 Reverse Drain Current vs. Sourse-Drain Voltage

GATE-SOURCE VOLTAGE : -V_{GS}[V]
Fig.11 Static Drain-Source On-State
Resistance vs. Gate Source Voltage

Fig.12 Switching Characteristics



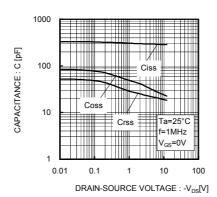


Fig.14 Typical Capacitance vs. Drain-Source Voltage

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● Measurement circuits

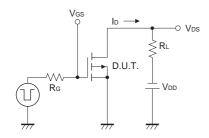


Fig.1-1 Switching Time Measurement Circuit

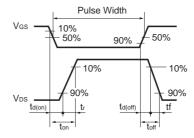


Fig.1-2 Switching Waveforms

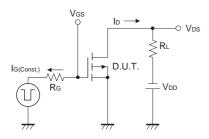


Fig.2-1 Gate Charge Measurement Circuit

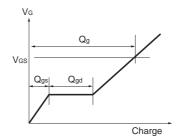


Fig.2-2 Gate Charge Waveform

Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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